

点胶式液态导热垫片 XK-S15LV®

特性：

1:1混合 (流淌式)
 1:1mix(no cure
 by-product)
 低应力應用
 low stress applications

操作方便
 Easy to Use

加熱加速反應
 Hear Fast Cure



應用：

汽車電子
 Automotive electronics
 通訊設
 Telecommunications
 電腦及周邊產品
 Computer & peripherals
 導熱，減震
 Thermally conductive
 vibration dampening
 熱源與散熱器間應用
 Between any
 heat-generating
 semiconductor and a heat
 sink

	XK-S15LV	METHOD	UNIT
Color / Part A	Gray	Visual	
Color / Part B	White	Visual	
Features	Soft GEL	-	-
Density	1.9	ASTM D792	g/cm3

Before Cured Property

A:B	1:1	-	-
Mixed Viscosity	230,000	ASTM D2196	cps
Shelf Life @ 25°C	6 month		

After Cured Property

Color	Gray	Visual	-
Cure Schedule 1	12hr/25°C		
Cure Schedule 2	10min/80°C		
Cure Schedule 3	5min/100°C		
Working time	60 Min/25°C		
Hardness	Shore 00 = 30	ASTM D2240	
	AskerC = 8	JIS K7312	
Tensile Strength.	0.7	ASTM D412	Mpa
Elongation	225	ASTM D412	%
Continuous Use Temp	-60~180		°C

Electrical Property

Dielectric strength	>10	ASTM D149	KV/mm
Volume resistivity	>10 ¹³	ASTM D257	Ohm-cm
Dielectric Constant	5.0	ASTM D150	(1Khz)
Flame Rating	V-0	UL94	

Thermal Property

Thermal Conductivity	1.5	ASTM D5470	W/m*K
Heat Capacity	1.0	ASTM E1269	J/g-K